

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HVC386B

Variable Capacitance Diode for VCXO



ADE-208-829 (Z)

Rev. 0
Nov. 1999

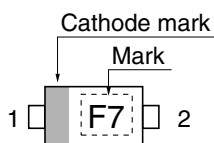
Features

- High capacitance ratio. ($n = 1.80$ min)
- Low series resistance. ($r_s = 0.85\Omega$ max)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC386B	F7	UFP

Pin Arrangement



1. Cathode
2. Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	$V_R = 15V$
	I_{R2}	—	—	100		$V_R = 15V, Ta = 60°C$
Capacitance	C_1	43.0	—	49.0	pF	$V_R = 1V, f = 1 MHz$
	C_4	18.5	—	25.5		$V_R = 4V, f = 1 MHz$
Capacitance ratio	n	1.80	—	—	—	C_1 / C_4
Series resistance	r_s	—	—	0.85	Ω	$V_R = 5V, f = 470 MHz$

Main Characteristic

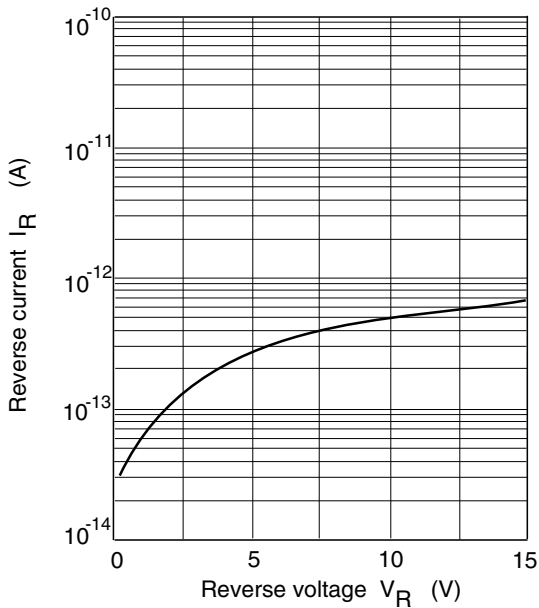


Fig.1 Reverse current Vs. Reverse voltage

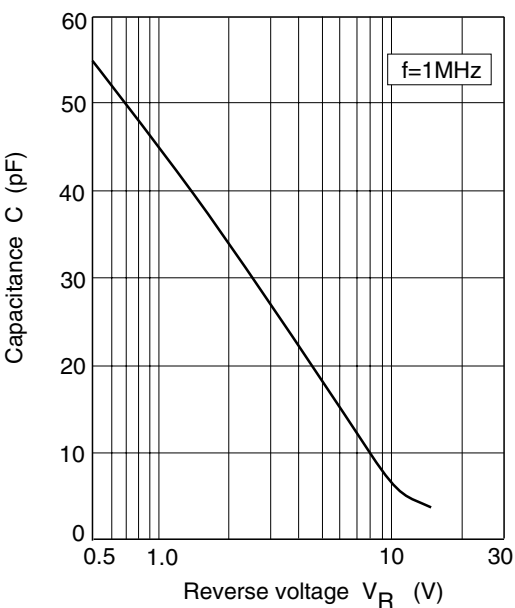


Fig.2 Capacitance Vs. Reverse voltage

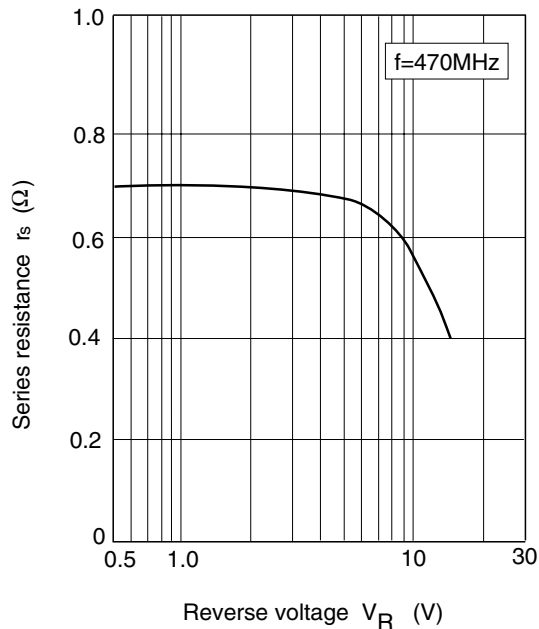


Fig.3 Series resistance Vs. Reverse voltage

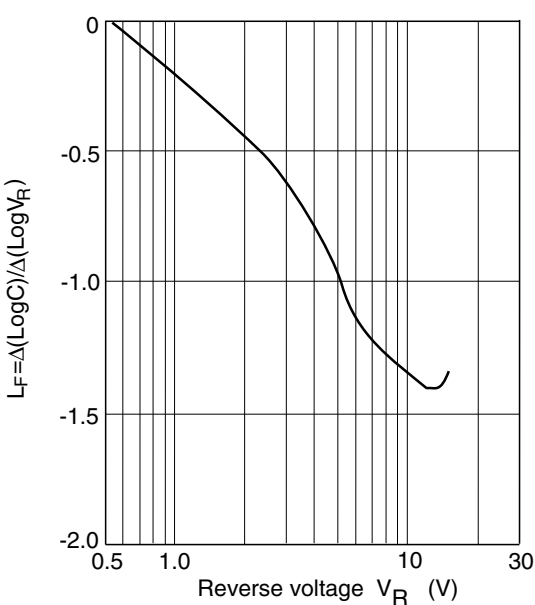
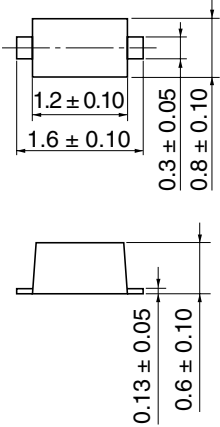


Fig.4 L_F Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	UFP
JEDEC	—
EIAJ	Conforms
Mass	0.0016 g

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